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# GOMACTech 2026

“Beyond the Noise”

New Orleans, LA

March 9 – 12, 2026

## Call for Papers

Established in 1968, GOMACTech is the premier forum for reviewing and reporting on developments in microcircuit technologies and applications for Government systems as well as announcements and updates of major government microelectronics and semiconductor initiatives. **GOMACTech is an unclassified, export-controlled event.** All registrants **must provide proof** of U.S. citizenship or permanent residence status and sign a non-disclosure agreement prior to being permitted entry into the conference.

GOMACTech 2026 will feature plenary sessions addressing the theme of **Beyond the Noise**, as well as a technical program describing the latest technological advances, including trustworthy and cyber-secure components/technologies, electro-optical components, RF components, micro-nano electronics, electronics integration, electronics materials, emerging neuromorphic electronics, quantum information/sensing technologies and technologies beyond Moore’s law, advances in wide and ultrawide-bandgap materials and device development, and novel power electronics.

Authors whose abstract is accepted—for oral and poster presentations—are required to submit a complete paper for the conference proceedings. Abstracts are solicited in the technical topic areas listed below. For additional, detailed descriptions of the technical topic areas, please go to the [GOMACTech website](#) → Paper Submission → Technical Topics.

[Submit abstracts here.](#)

**We are looking forward to your contributions!**

### Technical Topic Areas

Advanced Materials and Processes

Emerging Technologies

AI and ML in Microelectronics

High-Performance Digital and Mixed-signal Technologies

Packaging, Integration, Thermal, and Control Technologies

Photonic Technologies, Components, and Systems

Power Electronics and Emerging Power Technologies

Radiation-Hardened Technologies, Designs, and Systems

RF Technologies, Components, and Systems

Trusted, Assured and Cyber-secure Microelectronics

<b>2-page Abstract Due</b>	<b>Monday, September 22 2025</b>
<b>Author Notification</b>	<b>Friday, November 14, 2025</b>
<b>Final Full Paper Due</b>	<b>Friday, January 23, 2026</b>

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